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(54) **PACKAGE STACKING USING CHIP TO
WAFER BONDING**

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ABSTRACT

Embodiments are generally directed to package stacking
using chip to wafer bonding. An embodiment of a device
includes a first stacked layer including one or more semi-
conductor dies, components or both, the first stacked layer
further including a first dielectric layer, the first stacked layer
being thinned to a first thickness; and a second stacked layer
of one or more semiconductor dies, components, or both, the
second stacked layer further including a second dielectric
layer, the second stacked layer being fabricated on the first
stacked layer.

